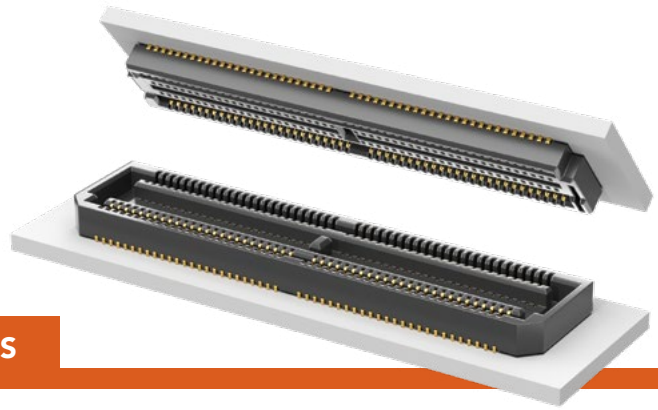


LOW PROFILE BLADE AND BEAM

(0.50 mm) .0197" PITCH • LTH/LSH SERIES



LTH
Mates:
LSH

LSH
Mates:
LTH

LTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
------------	---------------------------------	-----------	-----------------------	----------	----------	---------------------

-010, -020,
-030, -040, -050

-G
= 10 μm
(0.25 μm)
Gold

-K
= (5.50 mm)
.217" DIA
Polyimide
film Pick &
Place Pad

-TR
= Tape & Reel

-FR
= Full Reel
Tape & Reel
(must order max.
quantity per reel;
contact Samtec for
quantity breaks)

SPECIFICATIONS

Insulator Material:

Liquid Crystal
Polymer

Terminal Material:

Phosphor Bronze

Contact Material:

BeCu

Plating:

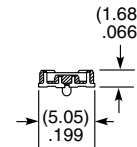
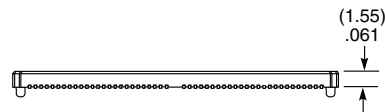
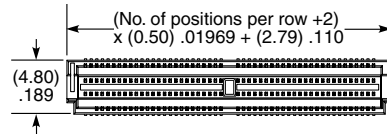
Au over 50 μm (1.27 μm) Ni

Current Rating:

2.6 A per pin
(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

Board Stacking:

For applications requiring more
than two connectors per board,
contact ipg@samtec.com

LSH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
------------	---------------------------------	-----------	-----------------------	----------	----------	---------------------

-010, -020,
-030, -040, -050

-G
= 10 μm
(0.25 μm)
Gold

-K
= (7.50 mm)
.295" DIA
Polyimide
film Pick &
Place Pad

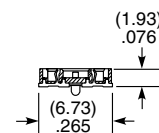
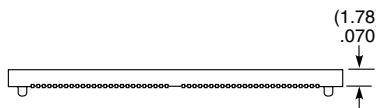
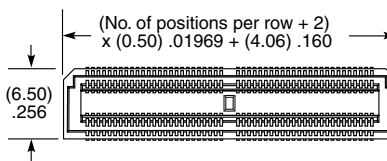
-TR
= Tape & Reel

-FR
= Full Reel
Tape & Reel
(must order max.
quantity per reel;
contact Samtec for
quantity breaks)

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(2.31 mm) .091"

*Processing conditions
will affect mated height.



Note:

Some lengths, styles and
options are non-standard,
non-returnable.